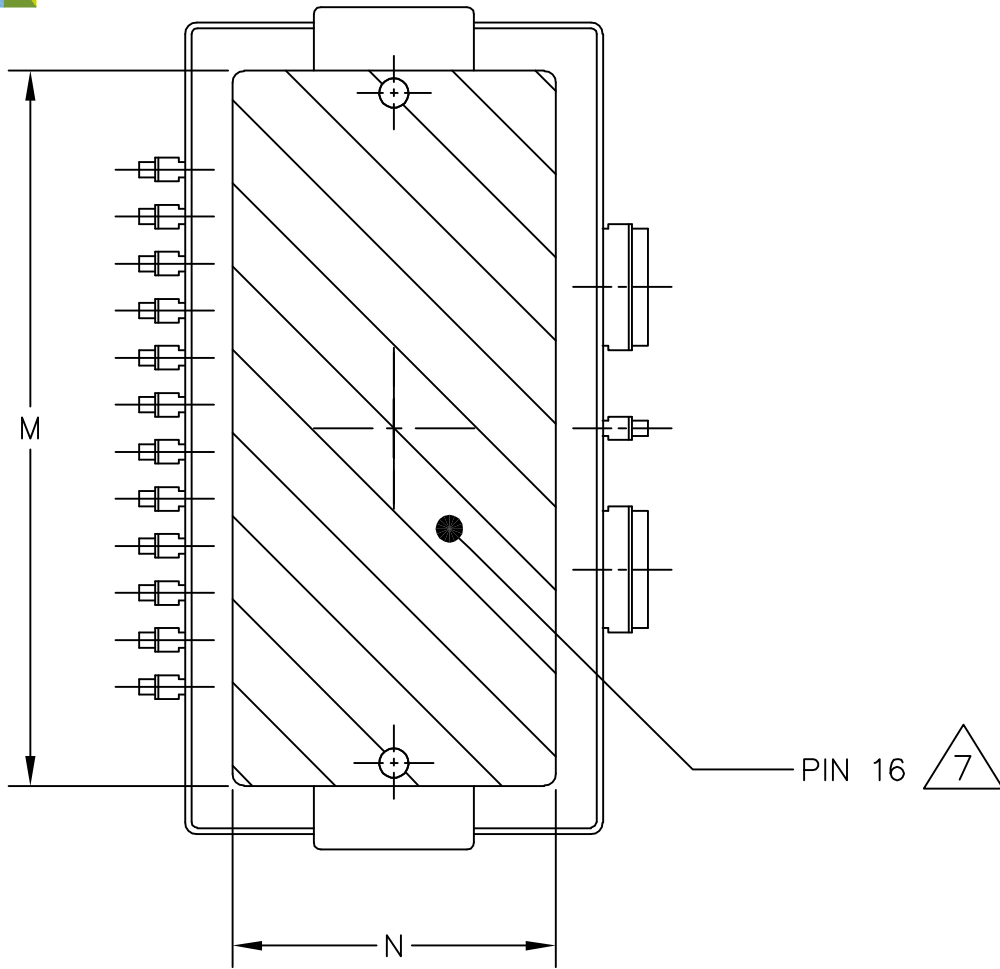
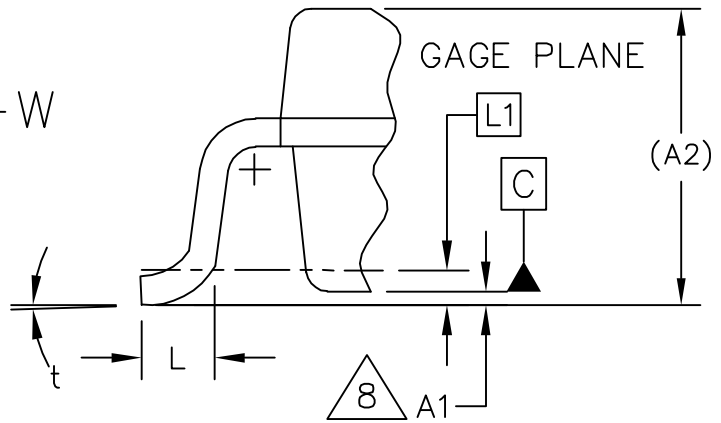


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VIEW W-W



DETAIL "Y"

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NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE. DIMENSIONS D AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS bb AND b1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE bb AND b1 DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. HATCHING REPRESENTS THE EXPOSED AND SOLDERABLE AREA OF THE HEAT SLUG. DIMENSIONS M AND N REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF THE HEAT SLUG.
8. DIMENSION A1 IS MEASURED WITH REFERENCE TO DATUM C. THE POSITIVE VALUE IMPLIES THAT THE BOTTOM OF THE PACKAGE IS HIGHER THAN THE BOTTOM OF THE LEAD.
9. THESE SURFACES OF THE HEAT SLUG ARE NOT PART OF THE SOLDERABLE SURFACES AND MAY REMAIN UNPLATED.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.099	.105	2.51	2.67	M	.600	----	15.24	----
A1	.001	.004	0.03	0.10	N	.270	----	6.86	----
A2	(.105)		(2.67)		bb	.097	.103	2.46	2.62
D	.688	.692	17.48	17.58	b1	.010	.016	0.25	0.41
D1	.712	.720	18.08	18.29	c1	.007	.011	0.18	0.28
E	.429	.437	10.90	11.10	e	.020 BSC		0.51 BSC	
E1	.353	.357	8.97	9.07	e1	.040 BSC		1.02 BSC	
E2	.346	.350	8.79	8.89	e2	.253 INFO ONLY		6.43 INFO ONLY	
E3	.132	.140	3.35	3.56	e3	.120 BSC		3.05 BSC	
L	.018	.024	0.46	0.61	t	2'	8'	2'	8'
L1	.010 BSC		0.25 BSC		aaa	.004		0.10	
					bbb	.008		0.20	

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